

Integrated Circuit Systems, Inc.

## ICS9148-25

## Pentium/Pro<sup>™</sup> System and Cyrix<sup>™</sup> Clock Chip

### **General Description**

The **ICS9148-25** is a Clock Synthesizer chip for Pentium and PentiumPro plus Cyrix CPU based Desktop/Notebook systems that will provide all necessary clock timing.

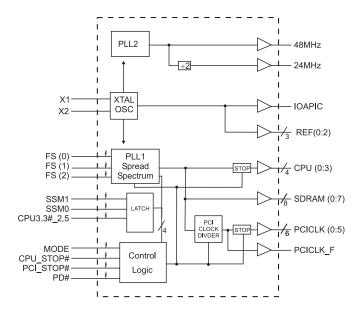
Features include four CPU, seven PCI and eight SDRAM clocks. Two reference outputs are available equal to the crystal frequency, plus the IOAPIC output powered by VDDL. Additionally, the device meets the Pentium power-up stabilization, which requires that CPU and PCI clocks be stable within 2ms after power-up.

High drive PCICLK and SDRAM outputs typically provide greater than 1 V/ns slew rate into 30pF loads. CPUCLK outputs typically provide better than 1V/ns slew rate into 20pF loads while maintaining  $50 \pm 5\%$  duty cycle. The REF clock outputs typically provide better than 0.5V/ns slew rates.

The **ICS9148-25** accepts a 14.318MHz reference crystal or clock as its input and runs on a 3.3V supply.

Sperad Spectrum is modulated in center-spread mode on CPU/ SDRAM/PCI clocks. Modulation amount is selectable at power-up (latched inputs) for  $\pm 0.5$ ,  $\pm 1.0$ ,  $\pm 2.0$  or No spreading.

### **Block Diagram**



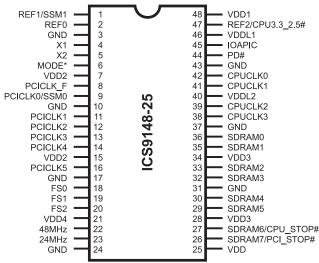
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9148-25 Rev B 5/20/99

### Features

- Generates system clocks for CPU, IOAPIC, SDRAM, PCI, plus 14.318 MHz ), USB, Plus Super I/O
- Spread spectrum for CPU/SDRAM/PCI clocks default
- Supports single or dual processor systems
- Modulation of Spread Spectrum selectable as  $\pm 0.5, \pm 1.0, \pm 2.0$  or none
- Supports Intel 60, 66.8MHz, Cyrix 55, 75MHz plus 83.3 and 68MHz (Turbo of 66.6) speeds.
- Synchronous clocks skew matched to 250ps window on CPU, SDRAM and 500ps window on PCI clocks
- CPU clocks to PCI clocks skew 1-4ns (CPU early)
- MODE input pin selects optional power management input control pins
- Two fixed outputs, 48MHz and 24 MHz
- Separate 2.5V and 3.3V supply pins
  - 2.5V or 3.3V output: CPU, IOAPIC (Strength selectable)
  - 3.3V outputs: SDRAM, PCI, REF, 48/24 MHz
- No power supply sequence requirements
- 48 pin 300 mil SSOP

### Pin Configuration



#### 48-Pin SSOP

#### Power Groups

VDD = Supply for PLL core. VDD1 = REF(0:2), X1, X2 VDD2 = PCICLK\_F, PCICLK(0:5) VDD3 = SDRAM(0:5), SDRAM6/CPU\_STOP#, SDRAM7/PCI\_STOP# VDD4 = 48MHz, 24MHz VDDL1 = IOAPIC VDDL2 = CPUCLK(0:3)

ICS reserves the right to make changes in the device data identified in this publication without further notice. ICS advises its customers to obtain the latest version of all device data to verify that any information being relied upon by the customer is current and accurate.



### **Pin Descriptions**

PIN NUMBER	PIN NAME	ТҮРЕ	DESCRIPTION
	SSM1	IN	Latched input for Spread Spectrum modulation amount
1			(see table)*
	REF1	OUT	Reference clock output
2	REF0	OUT	Reference clock output
3, 10, 17, 24, 31, 37, 43	GND	PWR	Ground (common)
4	X1	IN	Crystal or reference input, nominally 14.318 MHz. Includes internal load cap to GND and feedback resistor from X2.
5	X2	OUT	Crystal output, includes internal load cap to GND.
6	MODE	IN	Input function selection for Power Management pins*
7,15	VDD2	PWR	Supply for PCICLK_F, and PCICLK (0:5)
8	PCICLK_F	OUT	Free running PCI clock, not affected by PCI_STOP#
	PCICLK0	OUT	PCI clocks
9	SSM0	IN	Latched input for Spread Spectrum modulation amount (see table)*
11, 12, 13, 14, 16	PCI_CLK (1:5)	OUT	PCI clocks
18	FS0	IN	Frequency select 0 input*
19	FS1	IN	Frequency select 1 input*
20	FS2	IN	Frequency select 2 input*
21	VDD4	PWR	Supply for 48MHz and 24MHz clocks
22	48MHz	OUT	48MHz driver output for USB clock
23	24MHz	OUT	24MHz driver output for Super I/O
25	VDD	PWR	Supply for PLL core
26	SDRAM7	OUT	SDRAM clock
26	PCI_STOP#	IN	Halts PCI Bus (0:5) at next logic "0" level when low*
27	SDRAM6	OUT	SDRAM clock
27	CPU_STOP#	IN	Halts CPU clocks at next logic "0" level when low*
28,34	VDD3	PWR	Supply for SDRAM (0:5), SDRAM6/CPU_STOP#, SDRAM7/PCI_STOP
29, 30, 32, 33, 35, 36	SDRAM (0:5)	OUT	SDRAMs clock at CPU speed
38, 39, 41, 42	CPUCLK (0:3)	OUT	CPUCLK clock output, powered by VDDL2
40	VDD2	PWR	Supply for CPUCLK (0:3)
44	PD#	IN	Powers down chip, active low*
45	IOAPIC	OUT	IOAPIC clock output, powered by VDDL1, at crystal frequency
46	VDDL1	PWR	Supply for IOAPIC
47	CPU3.3_2.5#	IN	Latched 3.3 or 2.5 VDD buffer strength selection* (see table)
47	REF2	OUT	Reference clock output
48	VDD1	PWR	Supply for REF (0:2), X1, X2

\*Internal pull-up resistor of 120 to 150K to 3.3V on indicated inputs.

### Functionality

 $V_{DD}\!=\!3.3V\!\pm\!5\%\,V_{DDL}\!=\!2.5V\!\pm\!5\%$  or  $3.3V\!\pm\!5\%, T_{A}\!=\!0$  to  $70^{\circ}C$  Crystal (X1, X2) = 14.31818 MHz

FS2	FS1	FS0	CPUCLK, SDRAM (MHz)	PCICLK (MHz)
0	0	0	83.3	1/2 CPU
0	0	1	75	30 (CPU/2.5)
0	1	0	83.3	33.3 (CPU/2.5)
0	1	1	68.5	1/2 CPU
1	0	0	55	1/2 CPU
1	0	1	75	1/2 CPU
1	1	0	60	1/2 CPU
1	1	1	66.8	1/2 CPU



## Mode Pin - Power Management Input Control

MODE, Pin 6	Pin 26	Pin 27
0	PCI_STOP# Input	CPU_STOP# Input
1	SDRAM7 Output	SDRAM 6 Output

## **Power Management Functionality**

CPU_STOP#	PCI_STOP#	PD#	CPUCLK Outputs	PCICLK(0:5) Outputs	PCICLK_F, REF, 24/48MHz and SDRAM	Crystal OSC	VCO
Х	Х	0	Stopped Low	Stopped Low	Stopped Low	Off	Off
0	0	1	Stopped Low	Stopped Low	Running	Running	Running
0	1	1	Stopped Low	Running	Running	Running	Running
1	0	1	Running	Stopped Low	Running	Running	Running
1	1	1	Running	Running	Running	Running	Running

### Spread Spectrum Functionality

Latched Pin 1 SSM1	Latched Pin 9 SSM0	CPU, SDRAM and PCICLOCKS	REF, IOAPIC	24MHz	48MHz
0	0	Normal, steady frequency mode	14.318MHz	24MHz	48MHz
0	1	Frequency modulated in center spread ±2.0%	14.318MHz	24MHz	48MHz
1	0	Frequency modulated in center spread ±1.0%	14.318MHz	24MHz	48MHz
1*	1*	Frequency modulated in center spread ±0.5%	14.318MHz	24MHz	48MHz

\*default with internal pull-ups

### CPU 3.3\_2.5V Buffer selector for CPUCLK and IOAPIC drivers.

CPU3.3_2.5# Latched Input Level	Buffer Selected for Operation at:
0	2.5V VDD
1	3.3V VDD



### **Technical Pin Function Descriptions**

#### VDD(1,2,3,4)

This is the power supply to the internal core logic of the device as well as the clock output buffers for REF(0:1), PCICLK, 48/24MHzA/B and SDRAM(0:7).

This pin operates at 3.3V volts. Clocks from the listed buffers that it supplies will have a voltage swing from Ground to this level. For the actual guaranteed high and low voltage levels for the Clocks, please consult the DC parameter table in this data sheet.

#### VDDL1,2

This is the power supplies for the CPUCLK and IOAPCI output buffers. The voltage level for these outputs may be 2.5 or 3.3 volts. Clocks from the buffers that each supplies will have a voltage swing from Ground to this level. For the actual Guaranteed high and low voltage levels of these Clocks, please consult the DC parameter table in this Data Sheet. See control pin CPUCLK3.3\_2.5# for output buffer strength matching VDDL required for skew control.

#### GND

This is the power supply ground (common or negative) return pin for the internal core logic and all the output buffers.

#### X1

This input pin serves one of two functions. When the device is used with a Crystal, X1 acts as the input pin for the reference signal that comes from the discrete crystal. When the device is driven by an external clock signal, X1 is the device input pin for that reference clock. This pin also implements an internal Crystal loading capacitor that is connected to ground. See the data tables for the value of this capacitor. Also includes feedback resistor from X2.

#### X2

This Output pin is used only when the device uses a Crystal as the reference frequency source. In this mode of operation, X2 is an output signal that drives (or excites) the discrete Crystal. The X2 pin will also implement an internal Crystal loading capacitor that is connected to ground. See the Data Sheet for the value of this capacitor.

#### CPUCLK(0:3)

These Output pins are the Clock Outputs that drive processor and other CPU related circuitry that requires clocks which are in tight skew tolerance with the CPU clock. The voltage swing of these Clocks are controlled by the Voltage level applied to the VDDL2 pin of the device. See the Functionality Table for a list of the specific frequencies that are available for these Clocks and the selection codes to produce them. See control pin CPUCLK3.3\_2.5# for output buffer strength matching VDDL required for CPU to SDRAM skew control. These clocks are modulated by Sperad Spectrum.

#### **SDRAM(0:7)**

These Output Clocks are use to drive Dynamic RAM's and are low skew copies of the CPU Clocks. The voltage swing of the SDRAM's output is controlled by the supply voltage that is applied to VDD3 of the device, operates at 3.3 volts. These clocks are modulated by Sperad Spectrum.

#### 48MHz

This is a fixed frequency Clock output at 48MHz that is typically used to drive USB devices.

#### 24MHz

This pin is a fixed frequency clock output typically used to drive Super I/O devices.

#### IOAPIC

This Output is a fixed frequency Output Clock that runs at the Reference Input (typically 14.31818MHz). Its voltage level swing is controlled by VDDL1 and may operate at 2.5 or 3.3volts.

#### **REF(0:2)**

The REF Outputs are fixed frequency Clocks that run at the same frequency as the Input Reference Clock X1 or the Crystal (typically 14.31818MHz) attached across X1 and X2.

#### PCICLK\_F

This Output is equal to PCICLK(0:5) and is FREE RUNNING, and will not be stopped by PCI\_STP#. This clock is modulated by Spread Spectrum.

#### PCICLK(0:5)

These Output Clocks generate all the PCI timing requirements for a Pentium/Pro based system. They conform to the current PCI specification. They run at 1/2 CPU frequency, or CPU/2.5, see frequency table. These clocks are modulated by Sperad Spectrum.

#### FS (0,1,2)

These Input pins control the frequency of the Clocks at the CPU, PCICLK and SDRAM output pins. See frequency table. These pins are all Full-time inputs with a pull-up to VDD.

#### MODE

This Input pin is used to select the Input function of the Power Management I/O pins 26 and 27. An active Low will place pins in the Input mode and enable those stop clock functions. This pin is a full-time input with a pull-up to VDD.



### **Technical Pin Function Descriptions**

#### CPU3.3\_2.5#

This Input pin controls the CPU and IOAPIC output buffer strength for skew matching CPU and SDRAM outputs to compensate for the external VDDL supply condition. It is important to use this function when selecting power supply requirements for VDDL1,2. A logic "0" (ground) will indicate 2.5V operation and a logic "1" will indicate 3.3V operation. This pin has an internal pull-up to VDD. This pin is a latched input.

#### PD#

This is an asynchronous active Low Input pin used to Power Down the device into a Low Power state by not removing the power supply. The internal Clocks are disabled and the VCO and Crystal are stopped. Powered Down will also place all the Outputs in a low state at the end of their current cycle. The latency of Power Down will not be greater than 3ms. This pin is a Full-time input with a pull-up to VDD.

#### CPU\_STOP#

This is a active Low Input pin used to stop the CPUCLK clocks in an active low state. All other clocks will continue to run while this function is enabled. The CPUCLK's will have a turn OFF latency and a turn ON latency of 2 or 3 CPU clocks. This pin is a Full-time input with a pull-up to VDD.

#### PCI\_STOP#

This is a synchronous active Low Input pin used to stop the PCICLK (0:5) clocks in a low state. It will not effect PCICLK\_F or any other outputs. There is only one full PCI clock output for Turn OFF or Turn ON latency. This pin is a Full-time input with a pull-up to VDD.

#### SSM (0:1)

These pins define the input condition for the Spread Spectrum amount of modulation. See Spread Spectrum functionality table. Note that spreading is only done on the CPU/SDRAM/ PCI clocks no modulation is done on the REF, IOAPIC or PLL2 (24, 48MHz) outputs.

These latched input pins are defined at power-on for logic Hi or logic Low condition by external pull-up or pull-down resistors, or the internal pull-up resistor to VDD. See shared pin operation of Input/output pins on next page.



### Shared Pin Operation -Input/Output Pins

Pins 1, 9 & 47 on the **ICS9148-25** serve as dual signal functions to the device. During initial power-up, they act as input pins. The logic level (voltage) that is present on these pins at this time is read and stored into a 4-bit internal data latch. At the end of Power-On reset, (see AC characteristics for timing values), the device changes the mode of operations for these pins to an output function. In this mode the pins produce the specified buffered clocks to external loads.

To program (load) the internal configuration register for these pins, a resistor is connected to either the VDD (logic 1) power supply or the GND (logic 0) voltage potential. A 10 Kilohm(10K) resistor is used to provide both the solid CMOS programming voltage needed during the power-up programming period and to provide an insignificant load on the output clock during the subsequent operating period. There is no degradation to the output clocks from resistors as low as 2K ohm. The internal pull-up resistors can be used as the logic high program input. Figs. 1 and 2 show the recommended means of implementing this function. In Fig. 1 either one of the resistors is loaded onto the board (selective stuffing) to configure the device's internal logic. Figs. 2a and b provide a single resistor loading option where either solder spot tabs or a physical jumper header may be used.

These figures illustrate the optimal PCB physical layout options. These configuration resistors are of such a large ohmic value that they do not effect the low impedance clock signals. The layouts have been optimized to provide as little impedance transition to the clock signal as possible, as it passes through the programming resistor pad(s).

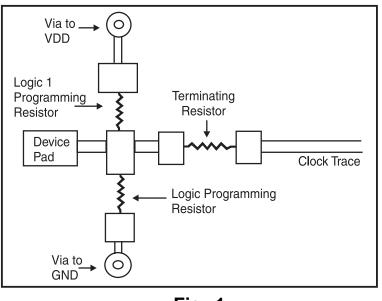


Fig. 1



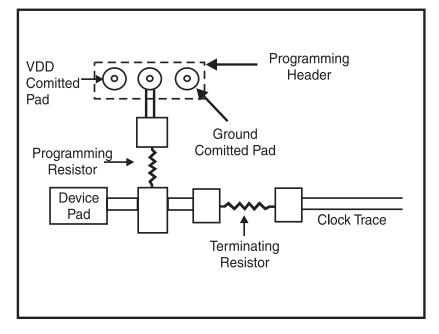


Fig. 2a

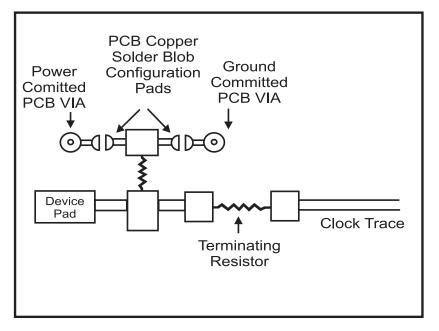


Fig. 2b



### Electrical Characteristics - Input/Supply/Common Output Parameters

, 115	<u> </u>	JDL = 3.3 V + -3% (unless otherwise stated)	-	1		
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input High Voltage	VIH		2		V <sub>DD</sub> +0.3	V
Input Low Voltage	VIL		Vss-0.3		0.8	V
Input High Current	IIH	$V_{\rm IN} = V_{\rm DD}$		0.1	5	μA
Input Low Current	IIL1	$V_{IN} = 0$ V; Inputs with no pull-up resistors	-5	2.0		μA
Input Low Current	IIL2	$V_{IN} = 0$ V; Inputs with pull-up resistors	-200	-100		μA
Operating Supply Current	Idd3.30p	$C_L = 0 \text{ pF}$ ; Select @ 66M		75	95	mA
Power Down	Idd3.3pd	$C_L = 0 \text{ pF}$ ; With input address to Vdd or GND		8	600	μA
Supply Current						
Input frequency	Fi	$V_{DD} = 3.3 V;$		14.318		MHz
Input Capacitance <sup>1</sup>	CIN	Logic Inputs			5	pF
	Cinx	X1 & X2 pins	27	36	45	pF
Transition Time <sup>1</sup>	Ttrans	To 1st crossing of target Freq.			3	ms
Settling Time <sup>1</sup>	Ts	From 1st crossing to 1% target Freq.		5		ms
Clk Stabilization <sup>1</sup>	TSTAB	From $V_{DD} = 3.3$ V to 1% target Freq.			3	ms
	TCPU-SDRAM1	$V_T = 1.5 \text{ V}$		200	500	ps
Skew <sup>1</sup>	TCPU-PCI1	$V_{T} = 1.5 V;$	1	2	4.5	ns
	TREF-IOAPIC	$V_{T} = 1.5 V;$		900		ps

TA = 0 - 70C; Supply Voltage VDD = VDDL =  $3.3 \text{ V} \pm 7.5\%$  (unless otherwise stated)

<sup>1</sup>Guarenteed by design, not 100% tested in production.

### Electrical Characteristics - Input/Supply/Common Output Parameters

 $T_A = 0$  - 70C; Supply Voltage  $V_{DD} = 3.3 \text{ V} \pm 75\%$ ,  $V_{DDL} = 2.5 \text{ V} \pm 75\%$  (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Operating	IDD2.50P	$C_L = 0 pF$ ; Select @ 66M		8	9.5	mA
Supply Current						
	TCPU-SDRAM2	$V_T = 1.5 V$ ; $V_{TL} = 1.25 V$ ; SDRAM Leads		250	500	ps
Skew <sup>1</sup>	TREF-IOAPIC	$V_T = 1.5 \text{ V}; V_{TL} = 1.25 \text{ V}; \text{ SDRAM Leads}$		260		ps
	TCPU-PCI2	VT = 1.5 V; VTL = 1.25 V; CPU Leads	1	2	4	ns



### **Electrical Characteristics - CPU**

 $T_A = 0 - 70C$ ;  $V_{DD} = 3.3 V + -5\%$ ,  $V_{DDL} = 2.5 V + -5\%$ ;  $C_L = 10 - 20 pF$  (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	Rdsp2b <sup>1</sup>	$V_{\rm O} = V_{\rm DD} * (0.5)$	10		25	Ω
Output Impedance	$R_{DSN2B}^{1}$	$V_{O} = V_{DD}*(0.5)$	10		25	Ω
Output High Voltage	Voh2b	$I_{OH} = -13.0 \text{ mA}$	2	2.2		V
Output Low Voltage	Vol2b	IOL = 14  mA		0.3	0.4	V
Output High Current	Іон2в	$V_{OH} = 1.7 V$		-25	-16	mA
Output Low Current	Iol2b	$V_{OL} = 0.7 V$	22	26		mA
Rise Time	tr2B <sup>1</sup>	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.0 \text{ V}$		1.35	1.6	ns
Fall Time	t <sub>f2B</sub> <sup>1</sup>	$V_{OH} = 2.0 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.2	1.6	ns
Duty Cycle	$d_{t2B}^{1}$	$V_{T} = 1.25 V$	45	50	55	ns
Skew	$t_{sk2B}^{1}$	$V_{T} = 1.25 V$		60	250	ps
	tjcyc-cyc2B <sup>1</sup>	$V_T = 1.25 \text{ V}$		150	250	ps
Jitter	tj1s2B <sup>1</sup>	$V_T = 1.25 \ V$		30	150	ps
	tjabs2B <sup>1</sup>	$V_T = 1.25 \text{ V}$	-250	80	+250	ps

<sup>1</sup>Guarenteed by design, not 100% tested in production.

### **Electrical Characteristics - PCI**

 $T_A = 0 - 70C; V_{DD} = V_{DDL} = 3.3 V + -5\%; C_L = 30 pF$  (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	$R_{DSP1}^{1}$	$V_{O} = V_{DD}^{*}(0.5)$	12		55	Ω
Output Impedance	$\mathbf{R}_{\mathrm{DSN1}}^{1}$	$V_{O} = V_{DD}^{*}(0.5)$	12		55	Ω
Output High Voltage	V <sub>OH1</sub>	$I_{OH} = -11 \text{ mA}$	2.6	3.1		V
Output Low Voltage	V <sub>OL1</sub>	$I_{OL} = 9.4 \text{ mA}$		0.15	0.4	V
Output High Current	I <sub>OH1</sub>	$V_{OH} = 2.0 V$		-62	-40	mA
Output Low Current	I <sub>OL1</sub>	$V_{OL} = 0.8 V$	40	55		mA
Rise Time	$t_{r1}^{1}$	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.5	2	ns
Fall Time	$t_{f1}^{1}$	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.4	2	ns
Duty Cycle	$d_{t1}^{1}$	$V_{\rm T} = 1.5  {\rm V}$	45	50	60	%
Skew	$t_{sk1}^{1}$	$V_{\rm T} = 1.5  {\rm V}$		200	500	ps
Jitter	$t_{j1s1}^{1}$	$V_{\rm T} = 1.5 \ {\rm V}$		10	150	ps
	t <sub>jabs1</sub> 1	$V_{\rm T} = 1.5 \ {\rm V}$	-250	65	250	ps



#### SYMBOL CONDITIONS MIN TYP PARAMETER MAX UNITS Rdsp3<sup>1</sup> Output Impedance $VO = VDD^*(0.5)$ 10 24 Ω Rdsn3<sup>1</sup> 10 Output Impedance $V_0 = V_{DD} * (0.5)$ 24 Ω V Output High Voltage $I_{OH} = -30 \text{ mA}$ 2.6 **V**онз 2.8 Output Low Voltage Vol3 IOL = 23 mA0.3 0.4 V Output High Current **І**ОН3 $V_{OH} = 2.0 V$ -40 -62 mA Output Low Current $V_{OL} = 0.8 V$ 40 55 Iol3 mA Tr3<sup>1</sup> VOL = 0.4 V, VOH = 2.4 VRise Time 1.5 2 ns $T_{\mathfrak{B}}^{1}$ Fall Time $V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$ 1.4 2 ns $D_{t3}^{1}$ Duty Cycle $V_{T} = 1.5 V$ 45 50 60 % Tsk3<sup>1</sup> $V_{T} = 1.5 V$ 500 Skew 200 ps Tj1s3 VT = 1.5 V Jitter 50 150 ps Tjabs3<sup>1</sup> $V_{T} = 1.5 V$ -250 100 250 ps

### Electrical Characteristics - SDRAM

 $T_A = 0 - 70C$ ;  $V_{DD} = V_{DDL} = 3.3 V + -5\%$ ;  $C_L = 20 - 30 pF$  (unless otherwise stated)

<sup>1</sup>Guarenteed by design, not 100% tested in production.

### **Electrical Characteristics - IOAPIC**

,	,	$L = 2.5 V + -5\%$ , $C_{L} = 10 - 20 \text{ pr}$ (unless otherw	1	,		
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	$R_{DSP4B}^{1}$	$V_{\rm O} = V_{\rm DD} * (0.5)$	10		30	Ω
Output Impedance	Rdsn4b <sup>1</sup>	$V_{\rm O} = V_{\rm DD} * (0.5)$	10		30	Ω
Output High Voltage	Voh4\b	$I_{OH} = -8 \text{ mA}$	2	2.5		V
Output Low Voltage	Vol4b	$I_{OL} = 12 \text{ mA}$		0.3	0.5	V
Output High Current	Іон4в	Vон = 1.7 V		-25	-16	mA
Output Low Current	IOL4B	$V_{OL} = 0.7 V$	19	23		mA
Rise Time	$t_{r4B}^{1}$	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.0 \text{ V}$		1.4	1.6	ns
Fall Time	$t_{\rm f4B}^1$	$V_{OH} = 2.0 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.2	1.6	ns
Duty Cycle	$d_{t4B}^{1}$	$V_{T} = 1.25 V$	40	53	60	%
	tjcyc-cyc4B <sup>1</sup>	$V_{T} = 1.25 V$		1400		ps
Jitter	tj1s4B <sup>1</sup>	$V_{T} = 1.25 V$		300	400	ps
	tjabs4B <sup>1</sup>	$V_{T} = 1.25 V$	-1000	800	1000	ps

 $T_A = 0 - 70C$ ;  $V_{DD} = 3.3 \text{ V} + -5\%$ ,  $V_{DDL} = 2.5 \text{ V} + -5\%$ ;  $C_L = 10 - 20 \text{ pF}$  (unless otherwise stated)



### Electrical Characteristics-REF1, 48MHz, & 24MHz

 $T_{A}$  = 0 - 70C;  $V_{DD}$  =  $V_{DDL}$  = 3.3 V +/-5%;  $C_{L}$  = 20 - 45 pF (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	Rdsp7	$V_{\rm O} = V_{\rm DD} * (0.5)$	10		24	Ω
Output Impedance	Rdsn7	$V_{\rm O} = V_{\rm DD} * (0.5)$	10		24	Ω
Output High Voltage	Voh7	$I_{OH} = -30 \text{ mA}$	2.6	2.75		V
Output Low Voltage	Vol7	$I_{OL} = 23 \text{ mA}$		0.3	0.4	V
Output High Current	Іон7	$V_{OH} = 2.0 V$		-62	-40	mA
Output Low Current	Iol7	$V_{OL} = 0.8 V$	40	50		mA
Rise Time	${\rm T_{r7}}^1$	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.4	2	ns
Fall Time	${{ m T_{f7}}^1}$	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.4	2	ns
Duty Cycle	${\rm D_{t7}}^1$	$V_T = 1.5 V$	45	54	55	%
	tjcyc-cyc7 <sup>1</sup>	$V_T = 1.5 V$		1400		ps
Jitter	$T_{j1s7}^{1}$	$V_T = 1.5 V$		210	400	ps
	${\rm T_{jabs7}}^1$	$V_T = 1.5 V$	-1000	450	1000	ps

<sup>1</sup>Guarenteed by design, not 100% tested in production.

### **Electrical Characteristics - REF0**

 $T_A = 0 - 70C; V_{DD} = V_{DDL} = 3.3 \text{ V} + -5\%; C_L = 20 - 45 \text{ pF} \text{ (unless otherwise stated)}$ 

	DL					
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	R <sub>DSP7</sub>	$V_{\rm O} = V_{\rm DD}^{*}(0.5)$	10		24	Ω
Output Impedance	R <sub>DSN7</sub>	$V_{\rm O} = V_{\rm DD}^{*}(0.5)$	10		24	Ω
Output High Voltage	V <sub>OH7</sub>	$I_{OH} = -30 \text{ mA}$	2.6	2.75		V
Output Low Voltage	V <sub>OL7</sub>	$I_{OL} = 23 \text{ mA}$		0.3	0.4	V
Output High Current	I <sub>OH7</sub>	$V_{OH} = 2.0 V$		-62	-54	mA
Output Low Current	I <sub>OL7</sub>	$V_{OL} = 0.8 V$	41	50		mA
Rise Time	$T_{r7}^{1}$	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.8	2.2	ns
Fall Time	${T_{f7}}^{1}$	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.8	2.2	ns
Duty Cycle	$\mathbf{D_{t7}}^1$	$V_{\rm T} = 1.5 \ {\rm V}$	40	54	60	%
	t <sub>jcyc-cyc7</sub> 1	$V_{\rm T} = 1.5 \ {\rm V}$		1400		ps
Jitter	$T_{j1s7}^{1}$	$V_{\rm T} = 1.5 \ {\rm V}$		350	400	ps
	${\rm T_{jabs7}}^1$	$V_{\rm T} = 1.5 \ {\rm V}$	-1000	900	1000	ps



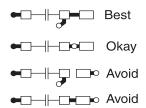
#### **General Layout Precautions:**

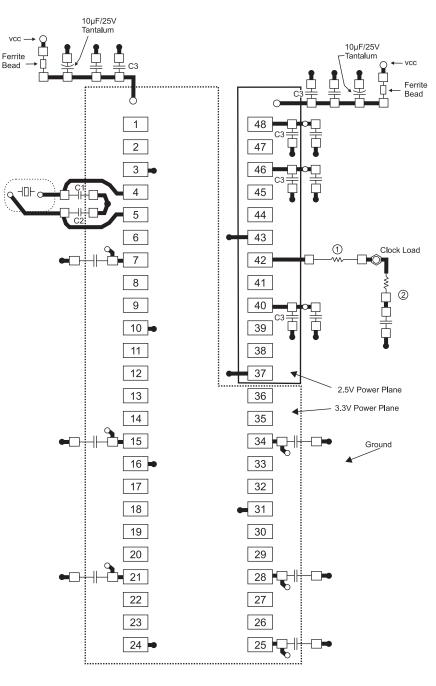
- 1) Use a ground plane on the top layer of the PCB in all areas not used by traces.
- 2) Make all power traces and vias as wide as possible to lower inductance.

#### Notes:

- 1) All clock outputs should have series terminating resistor. Not shown in all places to improve readibility of diagram.
- 2) 47 ohm / 56pf RC termination should be used on all over 50MHz outputs.
- 3) Optional crystal load capacitors are recommended.

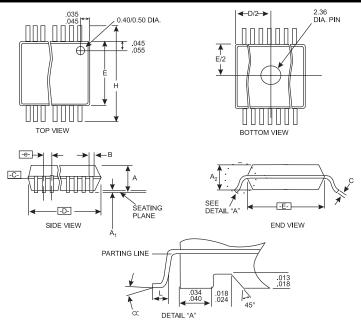
#### Connections to VDD:





- = Ground Plane Connection
- = Power Plane Connection
- = Solder Pads
- Clock Load





### **SSOP** Package

SYMBOL	COMMON DIMENSIONS			VARIATIONS	D			Ν
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
А	.095	.101	.110	AC	.620	.625	.630	48
A1	.008	.012	.016	AD	.720	.725	.730	56
A2	.088	.090	.092					
В	.008	.010	.0135					
С	.005	.006	.0085					
D	See Variations							
Е	.292	.296	.299					
e	0.025 BSC							
Н	.400	.406	.410					
h	.010	.013	.016					
L	.024	.032	.040					
N	See Variations							
~	0°	5°	8°					
Х	.085	.093	.100					

This table in inches

### **Ordering Information**

